

HX316LS9IBK2/16

16GB (8GB 1G x 64-Bit x 2 pcs.) DDR3L-1600
CL9 204-Pin SODIMM Kit



DESCRIPTION

HyperX HX316LS9IBK2/16 is a kit of two 1G x 64-bit (8GB) DDR3L-1600 CL9 SDRAM (Synchronous DRAM) 2Rx8, low voltage, memory modules, based on sixteen 512M x 8-bit DDR3 FBGA components per module. Total kit capacity is 16GB. Each module kit has been tested to run at DDR3L-1600 at a low latency timing of 9-9-9 at 1.35V or 1.5V. Additional timing parameters are shown in the PnP Timing Parameters section below. The JEDEC standard electrical and mechanical specifications are as follows:

Note: The PnP feature offers a range of speed and timing options to support the widest variety of processors and chipsets. Your maximum speed will be determined by your BIOS.

PnP JEDEC TIMING PARAMETERS:

- DDR3-1600 CL9-9-9 @1.35V or 1.5V
- DDR3-1333 CL8-8-8 @1.35V or 1.5V
- DDR3-1066 CL6-6-6 @1.35V or 1.5V

SPECIFICATIONS

| | |
|--------------------------------------------------|-------------------|
| CL(IDD) | 9 cycles |
| Row Cycle Time (tRCmin) | 48.125ns (min.) |
| Refresh to Active/Refresh Command Time (tRFCmin) | 260ns (min.) |
| Row Active Time (tRASmin) | 33.75ns (min.) |
| Maximum Operating Power | TBD W* @1.35V |
| UL Rating | 94 V - 0 |
| Operating Temperature | 0° C to 85° C |
| Storage Temperature | -55° C to +100° C |

*Power will vary depending on the SDRAM used.

FEATURES

- JEDEC standard 1.35V (1.28V ~ 1.45V) and 1.5V (1.425V ~ 1.575V) Power Supply
- VDDQ = 1.35V (1.28V ~ 1.45V) and 1.5V (1.425V ~ 1.575V)
- 800MHz fCK for 1600Mb/sec/pin
- 8 independent internal bank
- Programmable CAS Latency: 11, 10, 9, 8, 7, 6
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE ≤ 95°C
- Asynchronous Reset
- PCB : Height 1.180" (30.00mm), double sided component

Continued >>

